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Release-Conformal Film CMY-190NS

Release-Conformal Film CMY-190NS, PBT/TPEE-Foil based -190 µm thick, is best suited for the pressure equalization by Lamination of Cover-Layers to Flexible Printed Circuit Boards.

CMY-190NS when exposed to heat and pressure becomes extremely soft for the best conformance to complex flex part topographies. It reduces excessive "squeeze-out" and effectively drives adhesive or resin flow into designed areas.

CMY-190NS Features

- ▶ Silicon free
- ▶ inert, excellent release agent.
- ▶ it works with temperatures up to 180°C for 90min.
- ▶ clean, no foreign particle, no contamination of vacuum system

Product data

Description	Unit	Value	Test Method
Thickness	µm	190	Micrometer
Max Temp./ Cycletime	°C/min	180/90	ASTM D 3418
Tensile Strength	kgf/cm ²	MD 1.3 TD 1.2	ASTM D 882
Elongation after brake	%	MD 180 TD 150	
Heat shrinkage	%	MD <0.5 TD <0.5	ASTM D 1204 (150°C 10min)
Release resistance	gf/25mm	320	ASTM D 3330 KS M 3725
Melting Temperature	°C	235/90	ASTM 1525

Release-Conformal Film CMY-190NS, is available on 190µm thickness. (other thickness upon request). **CMY-190NS** is available in rolls or cut to size sheets from our Stock in Vétroz (Wallis).